February 4, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: MIYA

MIYAUCHI et al

Serial No.:

10/695,939

Filed:

October 30, 2003

For:

Functioning Substrate With A Group Of Columnar

Micro Pillars And Its Manufacturing Method

Group:

Examiner:

<u>UNDER 37 CFR 1.97 & 1.98</u>

Mail Stop: DD

Commissioner For Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In the matter of the above-identified application, applicants are submitting herewith a copy of a communication from a foreign patent office in a counterpart foreign application and copies of the documents listed in the attached form equivalent to Form PTO-1449 for the Examiner's consideration.

This information disclosure statement is being submitted before the mailing date of a first office action on the merits.

To the extent the documents listed on the attached form equivalent to Form PTO-1449 are not in the English language, the requirement of 37 CFR 1.98(a)(3) for a concise explanation of the relevance is satisfied by an English language version or the discussion of these documents in the specification.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit account of Antonelli, Terry, Stout & Kraus, LLP, Deposit Account No. 01-2135 (Case: 520.43241X00), and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

Atan E. Schiavelli

Registration No. 32,087

AES/jla (703) 312-6600 Attachments FO3M PTO-1449 (Rev. 4/92)

U.S. Department of Commerce Patent and Trademark Office

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

ATTY. DOCKET NO.

SERIAL NO.

10/695,939

520.43241X00 **APPLICANT**

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EXAMINER: Initial if citation is considered, draw line through citation if not in conformance and not consid r d.

Include copy of this form with n xt c mmunicati n t applicant.